

ABSTRACT

Object: To provide sufficient connection strength between the bonding pads and conductor wires in a wire bonding method.

- 5 Means for Solution: The bonding pads 20 upon a semiconductor chip 18 are provided with a bonding region 30 and a probe contact region 32, and one end of the conductor wire 22 is bonded to the bonding region 30. The probe contact to the probe contact region 32 is used for making contact to the tips of the test probes in the semiconductor chip inspection step performed prior to the bonding..

Selected Figure: Figure 3

Approved for Release